

65th ECTC Call for Papers

First Call For Papers IEEE 65th Electronic Components and Technology Conference www.ectc.net

To be held May 26 - May 29, 2015

at the Sheraton San Diego Hotel & Marina in San Diego, California, USA

The Electronic Components and Technology Conference (ECTC) is the premier international electronics symposium that brings together the best in packaging, components and microelectronic systems science, technology and education, in an environment of cooperation and technical exchange. ECTC is sponsored by the Components, Packaging and Manufacturing Technology (CPMT) Society of the IEEE. You are invited to submit abstracts that provide non-commercial information on new developments, technology and knowledge in the areas including, but not limited to, as given below under each technical program subcommittee name. Authors are encouraged to review the sessions of the previous ECTC programs to determine the committee selection for their abstracts.

Advanced Packaging:

3D integration, embedded, and wafer level packaging, flip chip, advanced substrates, novel assembly technologies, interposers, TSVs, MEMS & sensors, electronic (digital, analog, & RF), and optoelectronic & photovoltaic device packaging.

Applied Reliability:

Package reliability, characterization and test methods, interconnection reliability; solder and material characterization, and next generation/novel packaging reliability.

Assembly and Manufacturing Technology:

Assembly challenges and solutions, manufacturing aspects of 3D/TSV, manufacturing challenges of wafer thinning and flip chip processing.

Electronic Components & RF:

Components (including embedded components) and modules for RF/THz systems and bio applications, metamaterials, wireless sensors, RFID, RF MEMS, flexible & printed electronics, "green" RF electronics, wireless power transmission, power scavenging components, nano-based RF structures, and low-power RF designs.

Emerging Technologies:

Emerging packaging concepts and technologies, novel approaches to packaging, organic IC & TFT, microfluidics and MEMS, anti-counterfeiting packaging, and packaging for biosensing.

Interconnections:

First- and second-level interconnections: designs, structures, processes, performance, reliability, test including TSV, Si interposer, and interconnections for 3D integration, flip chip, solder bumping and Cu-pillar, wafer-level packaging, advanced wirebonds, non-traditional interconnections (e.g. ECA, CNT,

graphene, optical, etc.), electromigration for 2.5D and 3D, substrates and PCB solutions for the next generation systems, system packaging and heterogeneous integration.

Materials & Processing:

Adhesives and adhesion, lead free solder, novel materials and processing; underfills, mold compounds, and dielectrics, emerging materials and processing for 2D and 3D.

Modeling & Simulation:

Thermal, mechanical, electrical modeling and related measurements, 3D/TSV design and modeling, signal and power integrity, fracture and warpage in packages, material and fabrication modeling, first-level and second-level interconnects, high-speed interconnects.

Optoelectronics:

Fiber optical interconnects, active optical cables, parallel optical transceivers, silicon and III-V photonics devices, optical chip-scale and heterogeneous integration, micro-optical system integration and photonic system-in-package, optoelectronic assembly and reliability, materials and manufacturing technology, high-efficiency LEDs and high power lasers, and integrated optical sensors.

Interactive Presentations:

Papers may be submitted on any of the listed major topics; presentation of papers in an interactive format is highly encouraged at ECTC. Interactive presentations allow significant interaction between the presenter and attendees, and are especially suited for material that benefits from more explanation than is practical for oral presentations. Highly rated abstracts not fitting the theme of an oral session or submitted specifically for interactive presentation, and abstracts that are selected at the discretion of the program chair are included in the Interactive Presentation sessions.

You are invited to submit an abstract of no more than 750 words that describes the scope, content, and key points of your proposed paper via the website at www.ectc.net. If you have any questions, contact:

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Abstracts must be received by October 13, 2014. All abstracts must be submitted electronically at www.ectc.net. You must include the mailing address, business telephone number, and email address of presenting author(s) and affiliations of all authors with your submission.

Professional Development Courses

In addition to abstracts for papers, proposals are solicited from individuals interested in teaching educational professional development courses (4 hours) on topics described in the Call for Papers. Using the format "Course Objectives/Course Outline/Who Should Attend," 200-word proposals must be submitted via the website at www.ectc.net by October 13, 2014. If you have any questions, contact:

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